**Preferred Device** 

# Small Signal MOSFET 250 mAmps, 200 Volts

N-Channel TO-92

### **Features**

• Pb-Free Package is Available\*

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Drain - Source Voltage	V <sub>DS</sub>	200	Vdc
Gate-Source Voltage  - Continuous  - Non-repetitive (t <sub>p</sub> ≤ 50 μs)	V <sub>GS</sub> V <sub>GSM</sub>	±20 ±30	Vdc Vpk
Drain Current Continuous (Note 1) Pulsed (Note 2)	I <sub>D</sub>	250 500	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	350	mW
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- The Power Dissipation of the package may result in a lower continuous drain current.
- 2. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

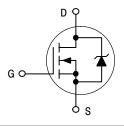


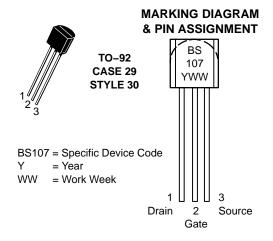
# ON Semiconductor®

http://onsemi.com

250 mA, 200 V  $R_{DS(on)} = 14~\Omega~(BS107)$   $R_{DS(on)} = 6.4~\Omega~(BS107A)$ 

#### N-Channel





# ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Zero-Gate-Voltage Drain Current (V <sub>DS</sub> = 130 Vdc, V <sub>GS</sub> = 0)	I <sub>DSS</sub>	-	_	30	nAdc
Drain–Source Breakdown Voltage (V <sub>GS</sub> = 0, I <sub>D</sub> = 100 μAdc)	V <sub>(BR)DSX</sub>	200	-	-	Vdc
Gate Reverse Current (V <sub>GS</sub> = 15 Vdc, V <sub>DS</sub> = 0)	I <sub>GSS</sub>	_	0.01	10	nAdc
ON CHARACTERISTICS (Note 3)					
Gate Threshold Voltage (I <sub>D</sub> = 1.0 mAdc, V <sub>DS</sub> = V <sub>GS</sub> )	V <sub>GS(Th)</sub>	1.0	_	3.0	Vdc
Static Drain–Source On Resistance BS107 ( $V_{GS} = 2.6 \text{ Vdc}$ , $I_D = 20 \text{ mAdc}$ ) ( $V_{GS} = 10 \text{ Vdc}$ , $I_D = 200 \text{ mAdc}$ ) BS107A ( $V_{GS} = 10 \text{ Vdc}$ ) ( $I_D = 100 \text{ mAdc}$ )	r <sub>DS(on)</sub>		- - 4.5	28 14 6.0	Ω
(I <sub>D</sub> = 250 mAdc)		-	4.8	6.4	
SMALL-SIGNAL CHARACTERISTICS  Input Capacitance (V <sub>DS</sub> = 25 Vdc, V <sub>GS</sub> = 0, f = 1.0 MHz)	C <sub>iss</sub>	-	60	_	pF
Reverse Transfer Capacitance (V <sub>DS</sub> = 25 Vdc, V <sub>GS</sub> = 0, f = 1.0 MHz)	C <sub>rss</sub>	-	6.0	_	pF
Output Capacitance $(V_{DS} = 25 \text{ Vdc}, V_{GS} = 0, f = 1.0 \text{ MHz})$	C <sub>oss</sub>	ı	30	_	pF
Forward Transconductance (V <sub>DS</sub> = 25 Vdc, I <sub>D</sub> = 250 mAdc)	9fs	200	400	_	mmhos
SWITCHING CHARACTERISTICS					
Turn-On Time	t <sub>on</sub>	-	6.0	15	ns
Turn-Off Time	t <sub>off</sub>	_	12	15	ns

<sup>3.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

# **RESISTIVE SWITCHING**

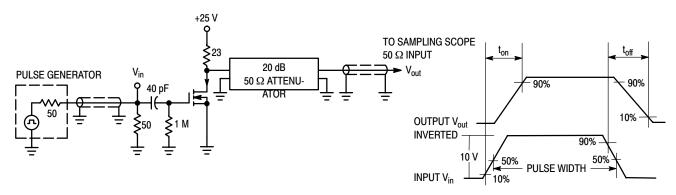


Figure 1. Switching Test Circuit

Figure 2. Switching Waveforms

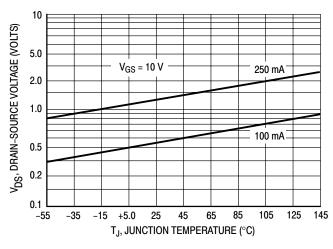


Figure 3. On Voltage versus Temperature

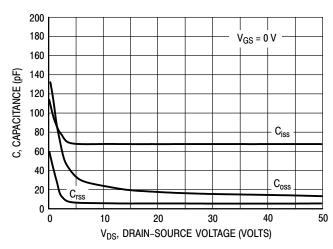


Figure 4. Capacitance Variation

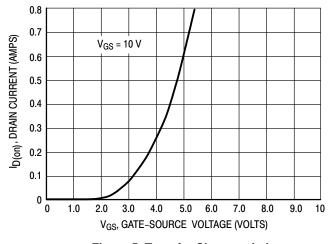


Figure 5. Transfer Characteristic

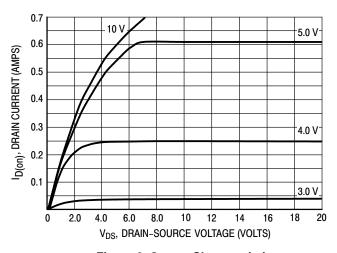


Figure 6. Output Characteristic

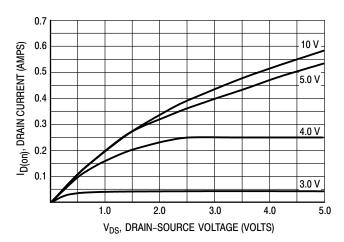


Figure 7. Saturation Characteristic

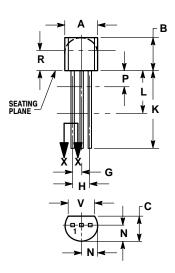
# **ORDERING INFORMATION**

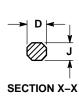
Device	Package	Shipping <sup>†</sup>	
BS107	TO-92	1000 Unit / Box	
BS107G	TO-92 (Pb-Free)		
BS107RLRA	TO-92	2000 / Tape & Reel	
BS107RL1	TO-92	2000 / Tape & Reel	
BS107A	TO-92		
BS107AG	TO-92 (Pb-Free)	1000 Units / Box	
BS107ARLRM	TO-92	2000 Ammo Pack	
BS107ARLRP	TO-92	2000 Ammo Pack	
BS107ARL1	TO-92		
BS107ARL1G	TO-92 (Pb-Free)	2000 / Tape & Reel	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **PACKAGE DIMENSIONS**

TO-92 (TO-226) CASE 29-11 **ISSUE AL** 





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
  4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCUES MILLIMETERS				
	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.175	0.205	4.45	5.20	
В	0.170	0.210	4.32	5.33	
С	0.125	0.165	3.18	4.19	
D	0.016	0.021	0.407	0.533	
G	0.045	0.055	1.15	1.39	
Н	0.095	0.105	2.42	2.66	
7	0.015	0.020	0.39	0.50	
K	0.500		12.70		
L	0.250		6.35		
N	0.080	0.105	2.04	2.66	
P		0.100		2.54	
R	0.115		2.93		
٧	0 135		3 43		

STYLE 30:
PIN 1. DRAIN
2. GATE
3. SOURCE

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